



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#51A  
11-21-01  
R. Mader

In re application of

RICHARD W. ARNOLD ET AL.

Serial No. 09/164,580 (TI-22561)

Filed October 1, 1998

For: KNOWN GOOD DIE USING EXISTING PROCESS INFRASTRUCTURE

Art Unit 2822

Examiner J. Mitchell

Commissioner for Patents  
Washington, D. C. 20231

Sir:

**AMENDMENT UNDER 37 C.F.R. 1.111**

In response to the Office action dated August 29, 2001, please amend the above identified application as follows:

**In the claims:**

Amend claim 1 as follows:

1. (Amended) An apparatus for testing a semiconductor die which comprises:

(a) a package having a cavity therein;

(b) a plurality of terminals in said package disposed at the periphery of said cavity;

(c) a semiconductor die to be tested having a plurality of bond pads thereon, said die disposed in said cavity;